

SOLIDWORKS GENERATED DRAWING, DO NOT CHANGE BY HAND

REV.	ECN. NO.	APPD.
A	BC-13-0069767	C.S Li

NOTES:

1. ELECTRICAL CHARACTERISTICS:

1.1. CONTACT CURRENT RATING: 0.5 AMPERE MAX. PER PIN.

1.2. VOLTAGE RATING: 25V AC.

1.3. INSULATION RESISTANCE: 100 MEGAOHMS MIN. AT 500V DC.

1.4. DIELECTRIC WITHSTANDING VOLTAGE: 250V AC RMS AT 60Hz, FOR 1 MINUTE.

1.5. CONTACT RESISTANCE: 60 MILLIOHMS MAX. PER PIN INITIAL

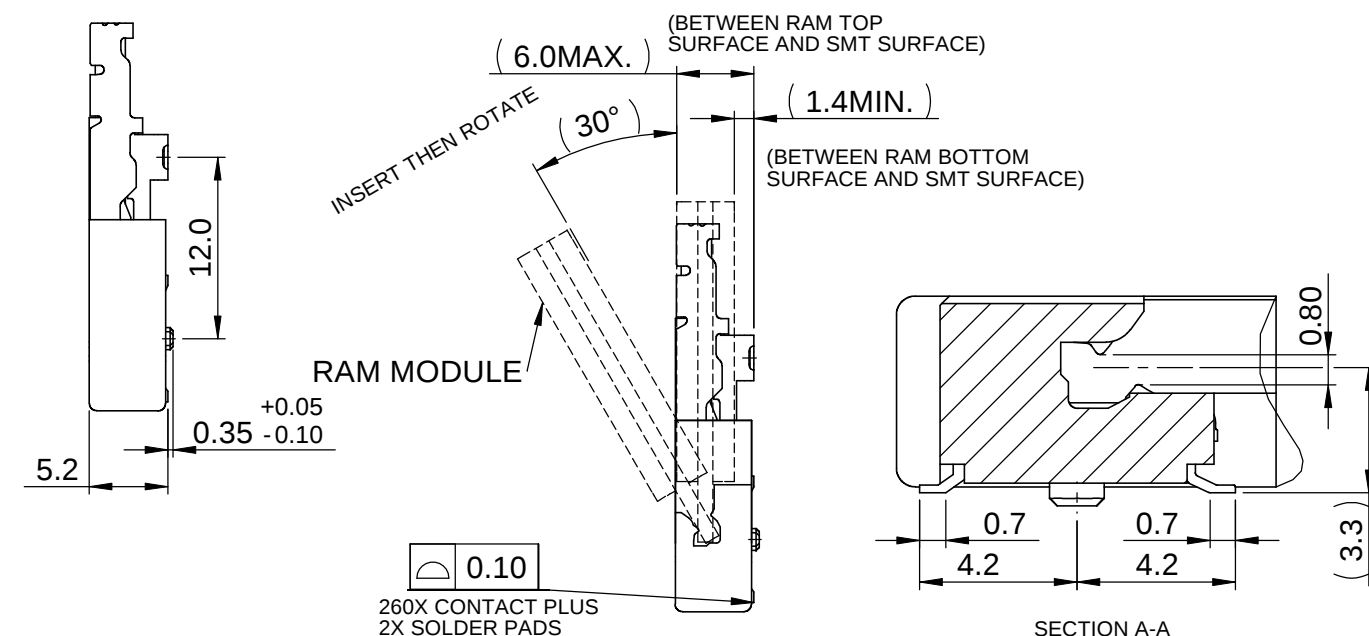
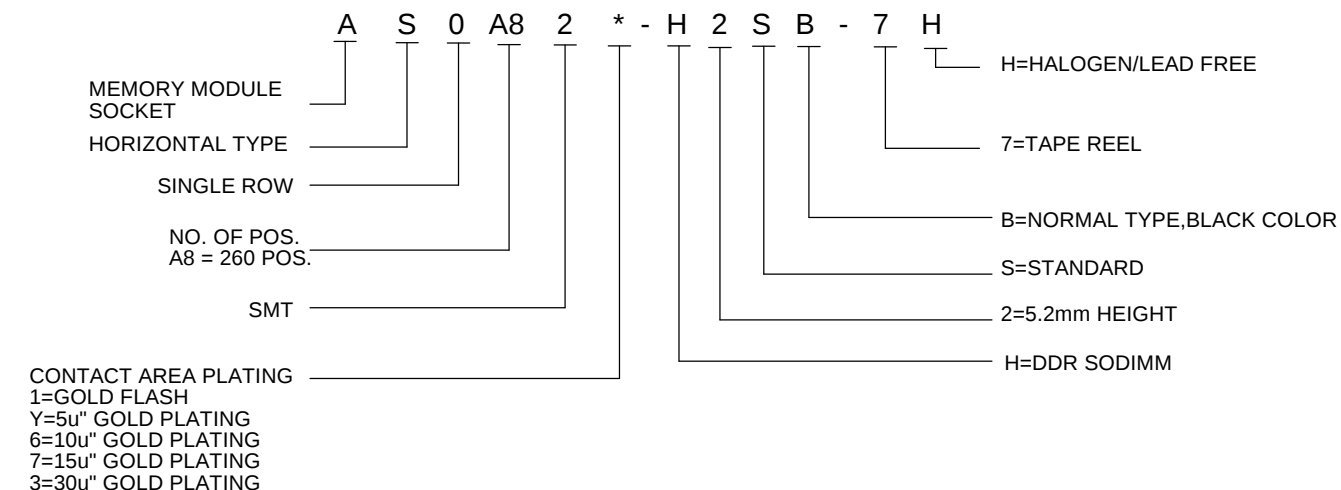
Δ10 MILLIOHMS PER PIN AFTER FULL ENVIRONMENTAL TESTING.

2. MECHANICAL CHARACTERISTICS: DURABILITY: 60 MATING CYCLES.

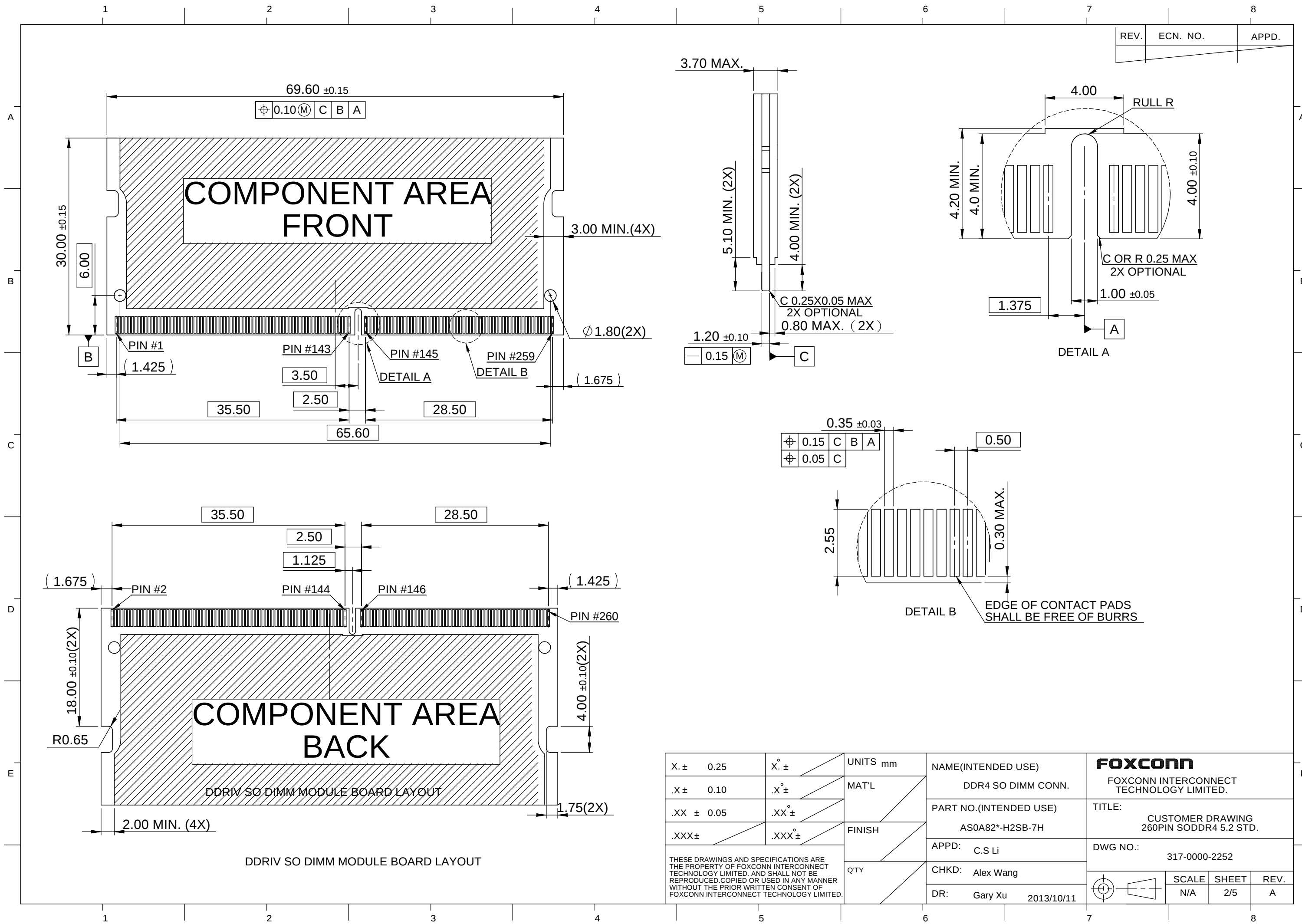
3. OPERATION TEMPERATURE: -55 °C TO +85 °C.

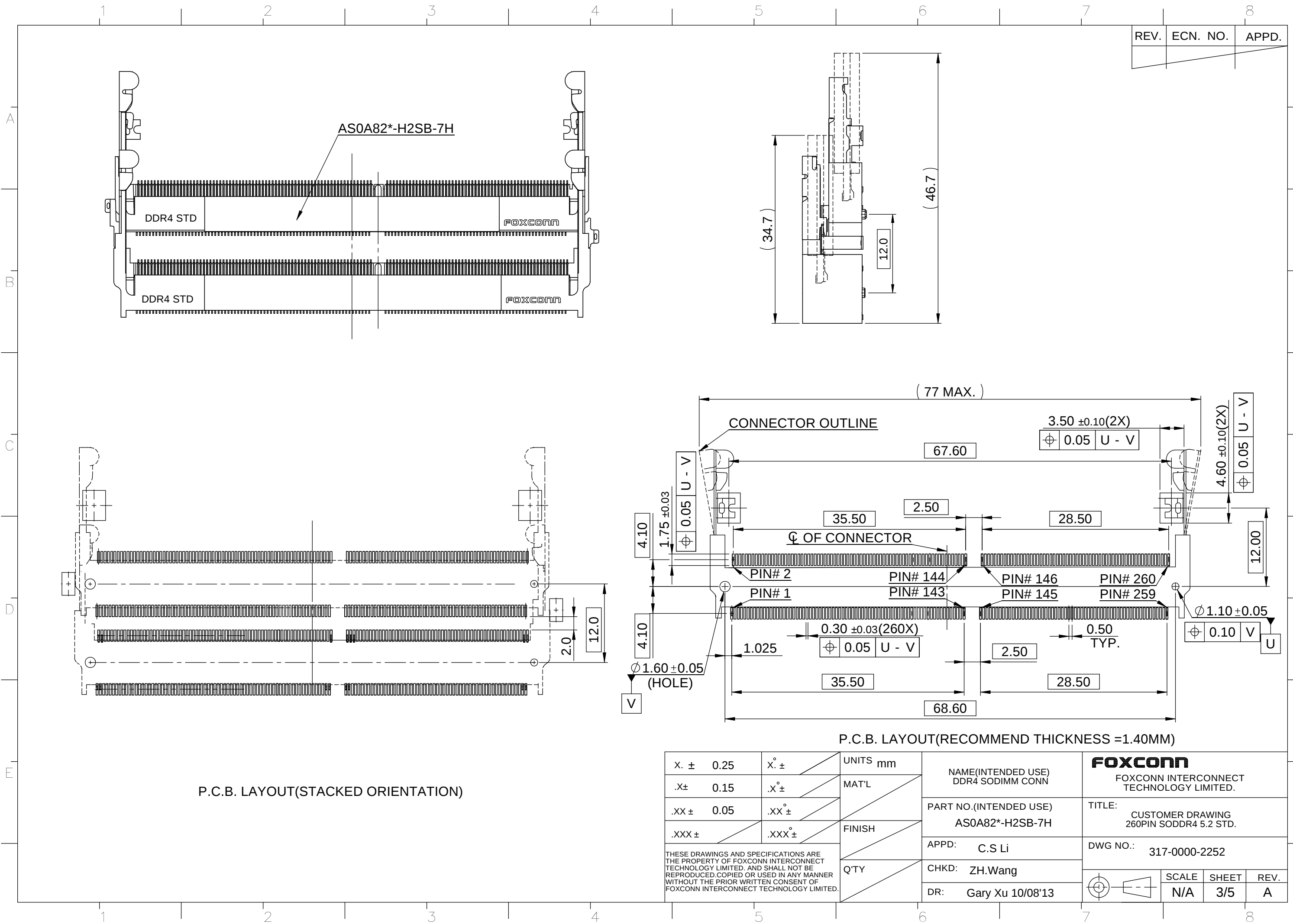
4. RECOMMENDED PROCESS CONDITION: SMT, PEAK TEMPERATURE: 260 °C 10~20S.

5. PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAILS & AVAILABILITY.



X.±	0.30	X.°±	UNITS	mm	NAME(INTENDED USE)	FOXCONN FOXCONN INTERCONNECT TECHNOLOGY LIMITED.		
.X±	0.25	.X°±	MAT'L		DDR4 SO DIMM CONN.	TITLE:		
.XX ±	0.15	.XX°±			PART NO.(INTENDED USE)	CUSTOMER DRAWING 260PIN SODDR4 5.2 STD.		
.XXX±		.XXX°±	FINISH		AS0A82*-H2SB-7H	DWG NO.:		
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED. AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.					APPD:	C.S Li	317-0000-2252	
					CHKD:	Alex Wang		SCALE
					DR:	Gary Xu 2013/10/11		
							SHEET	1/5
							REV.	A

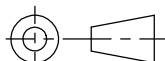


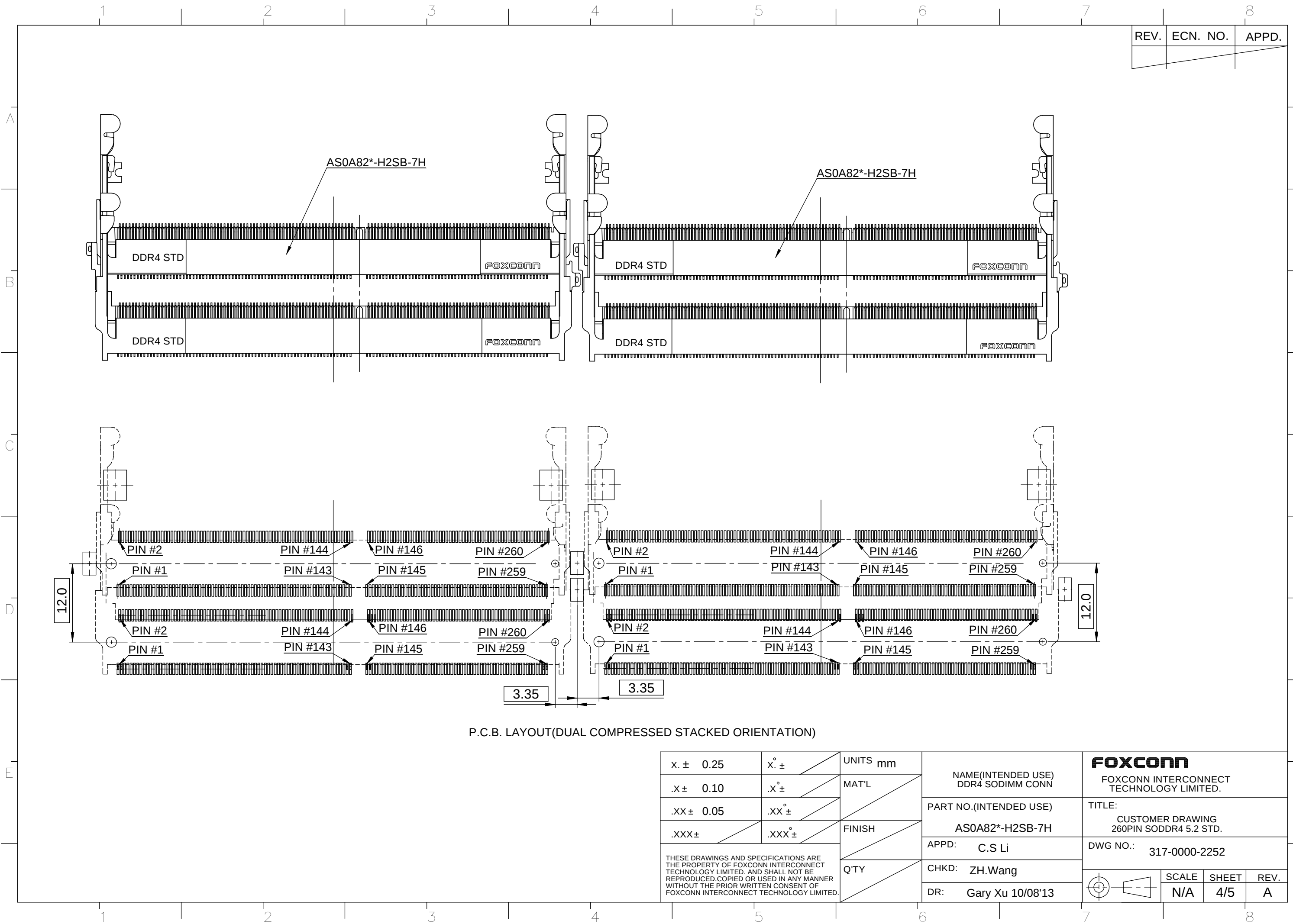


REV.	ECN. NO.	APPD.

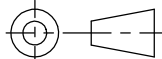
P.C.B. LAYOUT(STACKED ORIENTATION)

P.C.B. LAYOUT(RECOMMEND THICKNESS =1.40MM)

X. ± 0.25	X°. ±	UNITS mm	NAME(INTENDED USE) DDR4 SODIMM CONN	FOXconn FOXCONN INTERCONNECT TECHNOLOGY LIMITED.			
.X± 0.15	.X°. ±						
.XX ± 0.05	.XX°. ±	FINISH	PART NO.(INTENDED USE) AS0A82*-H2SB-7H	TITLE: CUSTOMER DRAWING 260PIN SODDR4 5.2 STD.			
.XXX ±	.XXX°. ±		Q'TY	APPD: C.S Li	DWG NO.: 317-0000-2252		
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		DR: Gary Xu 10/08'13			N/A	3/5	A



P.C.B. LAYOUT(DUAL COMPRESSED STACKED ORIENTATION)

X. ± 0.25	X.° ±	UNITS mm	NAME(INTENDED USE) DDR4 SODIMM CONN	FOXCONN FOXCONN INTERCONNECT TECHNOLOGY LIMITED.			
.X ± 0.10	.X.° ±			MAT'L	PART NO.(INTENDED USE) AS0A82*-H2SB-7H	TITLE: CUSTOMER DRAWING 260PIN SODDDR4 5.2 STD.	
.XX ± 0.05	.XX.° ±	FINISH	APPD: C.S Li			DWG NO.: 317-0000-2252	
.XXX ±	.XXX.° ±			Q'TY	CHKD: ZH.Wang		SCALE
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